

ABSTRACT

A method and system for preventing wafer breakage during wet processing is described. A wet processing tank is provided wherein a wafer is to be placed within the wet processing tank. A sensor is provided within the wet processing tank wherein the sensor continuously counts bubbles formed within the wet processing tank in a time interval. The sensor is queried wherein if a bubble count within the time interval exceeds a trigger point, then an alarm is given so that a process lot will not be entered into the wet processing tank.